

NOTES:

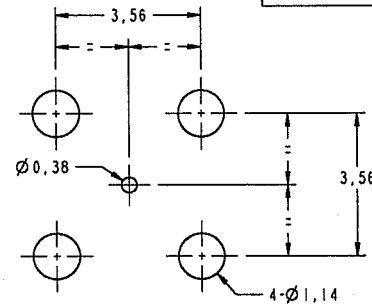
1. MATERIAL AND FINISH (PLATING THICKNESS IN MICRO-INCHES):
BODY - PHOSPHOR BRONZE, GOLD PLATING
CONTACT - BERYLLIUM COPPER, GOLD PLATING
INSULATOR - PEEK, NATURAL

2. 2 X PRE-TIN SQ. LEGS AND (Ø0.28) CONTACT POST WITH 63/37 Sn/Pb SOLDER, ACHIEVING APPROX. UNIFORM THICKNESS BUILD UP. A SOLDER-FREE REGION EXTENDING NO MORE THAN 0.76 FROM PWB MATING SURFACE IS PERMISSIBLE.

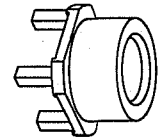
THIRD ANGLE PROJ.

REVISIONS

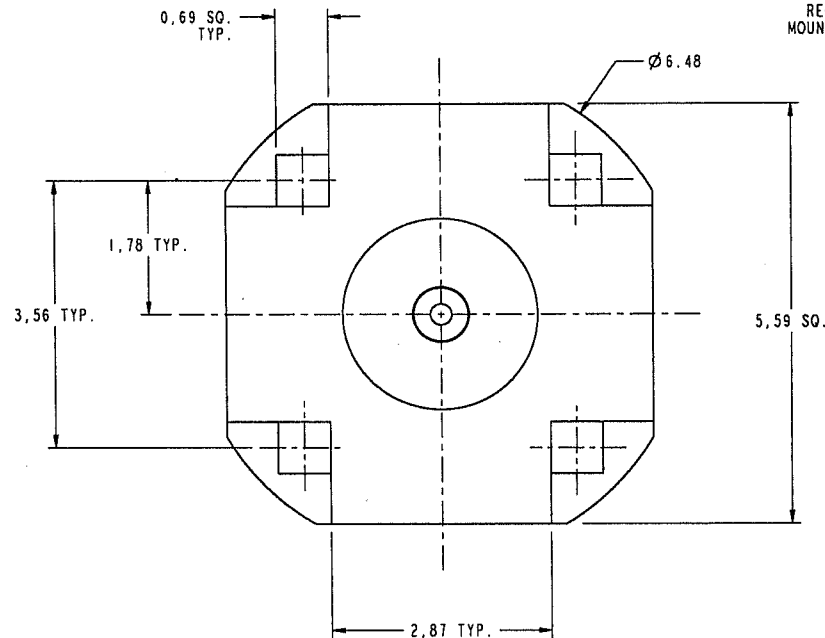
REV	DESCRIPTION	DATE	ECO	APPR
A	RELEASE TO MFG	27 Feb-08	46942	15-291



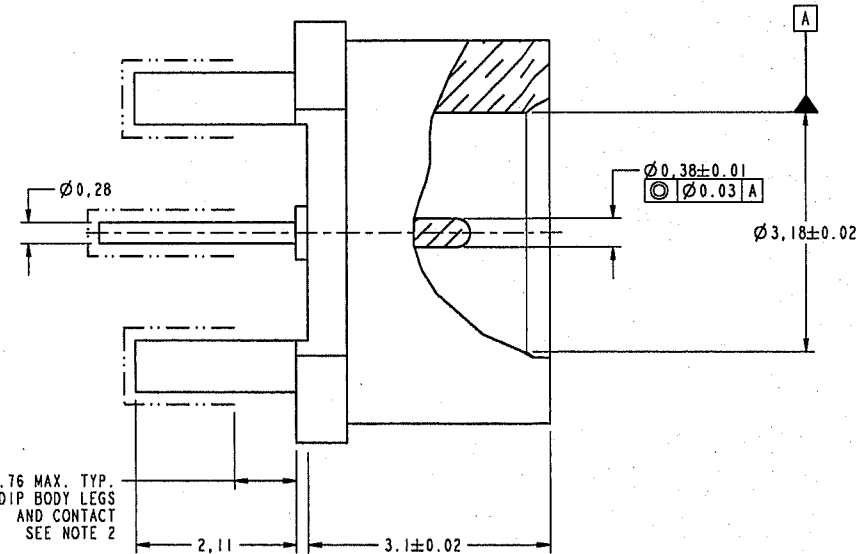
RECOMMENDED PCB
MOUNTING DIMENSIONS



SCALE 4.000



0.76 MAX. TYP.
TIN DIP BODY LEGS
AND CONTACT
SEE NOTE 2



CUSTOMER OUTLINE DRAWING

ALL OTHER SHEETS ARE FOR INTERNAL USE ONLY

UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE IN METRIC AND TOLERANCES ARE:
0.5 - 6mm ±0.1mm
6 - 30mm ±0.2mm
30 - 120mm ±0.3mm
ANGLES ±1°

NOTICE - These drawings, specifications, or other data (1) are, and remain the property of Amphenol Corp., (2) must be returned upon request; and (3) are confidential and not to be disclosed to any person other than those to whom they are given by Amphenol Corp., or to any other person to anyone for any purpose is not to be regarded by implication or otherwise in any manner licensing, granting rights to permitting such holder or any other person to manufacture, use or sell any product, process or design, patented or otherwise, that may in any way be related to or disclosed by said drawings, specifications, or other data.

MATERIAL

REFERENCE

CONFIGURATION LEVEL: Release

FINISH

DRAWN
H. PARIKH

ENGINEER
H. PARIKH

APPROVED
M. HOYACK

CAD FILE

I:\SMP\SMP-MSSB-PCT-4

DATE
15-Jun-06

DATE
15-Jun-06

DATE
1/31/08

TITLE
SMP TYPE
PCB THRU HOLES
SMOOTH BORE

SCALE: 15.0:1.0 SHEET 2 OF 2

DWG SIZE
B

CODE ID
74868

REV
A

Amphenol RF
Danbury CT USA, Tainan, Taiwan, Shenzhen, China
www.amphenolrf.com

DRAWING NO. SMP-MSSB-PCT-4

ITEM NO. SMP-MSSB-PCT-4

PART NO. SMP-MSSB-PCT-4